Static @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-100	—	—	V	V_{GS} = 0V, I_D = -250µA
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	-0.11	—	V/°C	Reference to 25°C, I_D = -1mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	60	mΩ	V_{GS} = -10V, I_D = -38A ④
$V_{GS(th)}$	Gate Threshold Voltage	-2.0	—	-4.0	V	V_{DS} = V_{GS}, I_D = -250µA
gfs	Forward Trans conductance	9.5	—	—	S	V_{DS} = -50V, I_D = -23A
I_{DSS}	Drain-to-Source Leakage Current	—	—	-50	µA	V_{DS} = -100V, V_{GS} = 0V
		—	—	-250		V_{DS} = -80V,V_{GS} = 0V,T_J =125°C
I_{GSS}	Gate-to-Source Forward Leakage	—	—	-100	nA	V_{GS} = -20V
	Gate-to-Source Reverse Leakage	—	—	100		V_{GS} = 20V

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

Q_g	Total Gate Charge	—	150	230	nC	I_D = -23A
Q_{gs}	Gate-to-Source Charge	—	22	33		V_{DS} = -80V
Q_{gd}	Gate-to-Drain Charge	—	81	120		V_{GS} = -10V④
$t_{d(on)}$	Turn-On Delay Time	—	14	—	ns	V_{DD} = -50V
t_r	Rise Time	—	63	—		I_D = -23A
$t_{d(off)}$	Turn-Off Delay Time	—	72	—		R_G= 2.4Ω
t_f	Fall Time	—	55	—		V_{GS} = -10V ④
L_D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6mm (0.25in.) from package and center of die contact 
L_S	Internal Source Inductance	—	7.5	—		
C_{iss}	Input Capacitance	—	2780	—	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	—	800	—		V_{DS} = -25V
C_{rss}	Reverse Transfer Capacitance	—	430	—		f = 1.0MHz, See Fig. 5

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	-38	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	-140		
V_{SD}	Diode Forward Voltage	—	—	-1.6	V	T_J = 25°C,I_S = -23A,V_{GS} = 0V ④
t_{rr}	Reverse Recovery Time	—	170	260	ns	T_J = 25°C ,I_F = -23A, V_{DD} = -25V
Q_{rr}	Reverse Recovery Charge	—	1180	1770	nC	di/dt = -100A/µs ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Notes:

① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)

② Limited by T_{Jmax} , starting T_J = 25°C, L = 0.46mH, R_G = 25Ω, I_{AS} = -23A.(See Fig.12)

③ $I_{SD} \leq$ -23A, di/dt ≤ -650A/µs, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq$ 150°C.

④ Pulse width ≤ 300µs; duty cycle ≤ 2%.

⑤ This is applied to D^2Pak When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994

⑥ R_θ is measured at T_J of approximately 90°C.

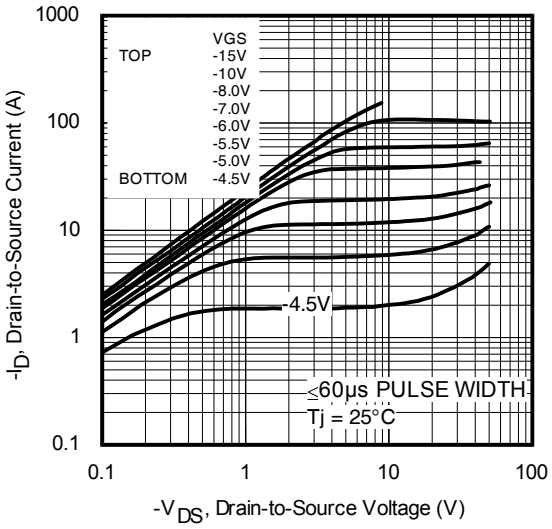


Fig. 1 Typical Output Characteristics

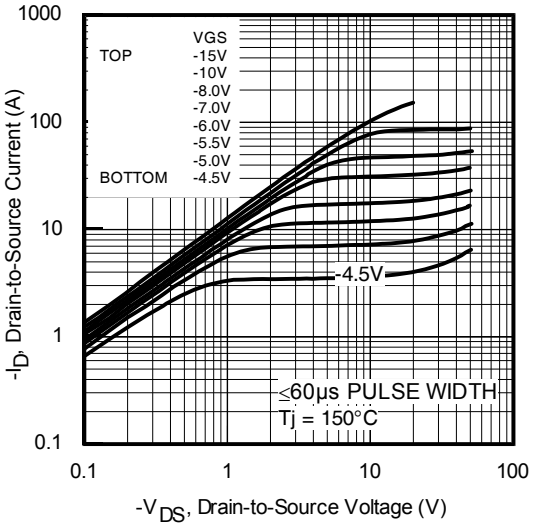


Fig. 2 Typical Output Characteristics

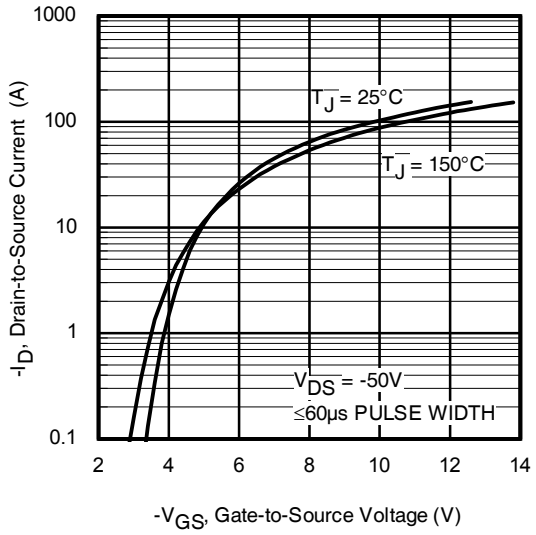


Fig. 3 Typical Transfer Characteristics

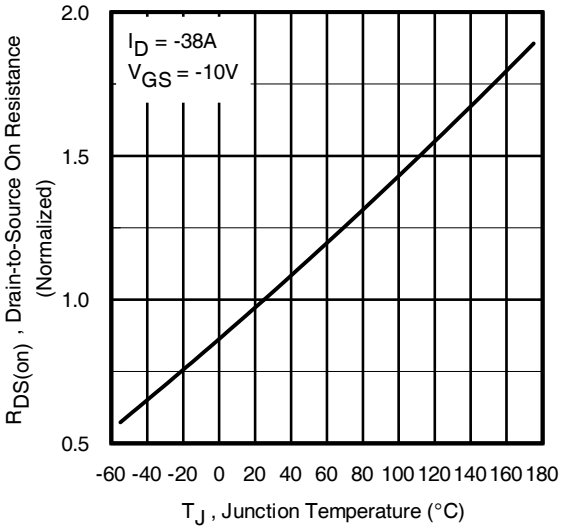


Fig. 4 Normalized On-Resistance vs. Temperature

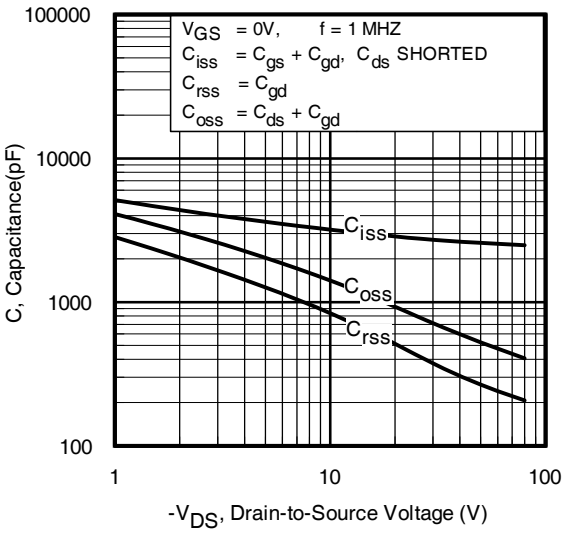


Fig 5. Typical Capacitance vs. Drain-to-Source Voltage

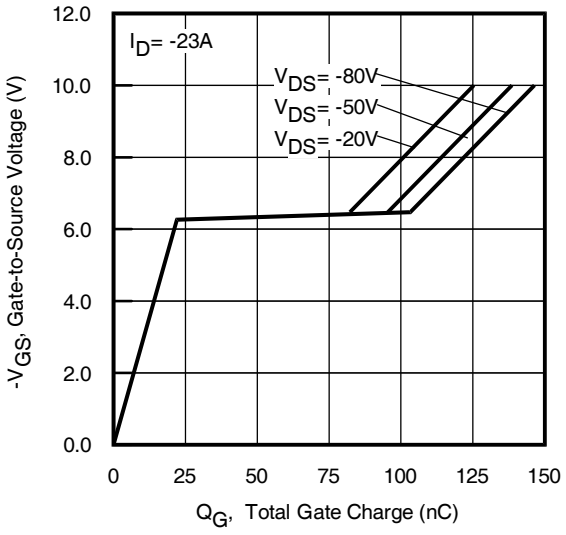


Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage

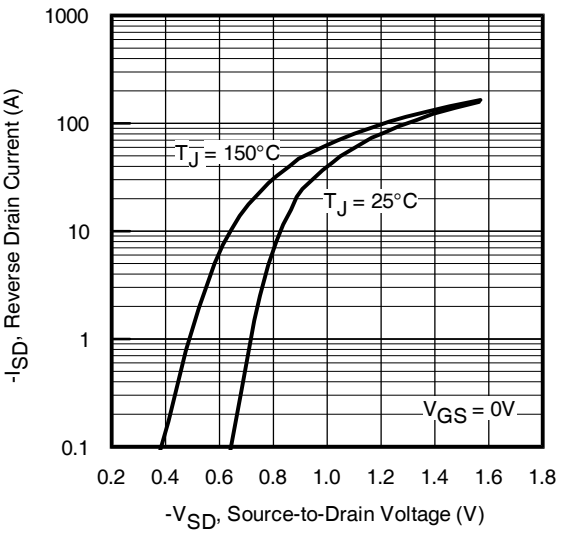


Fig. 7 Typical Source-to-Drain Diode Forward Voltage

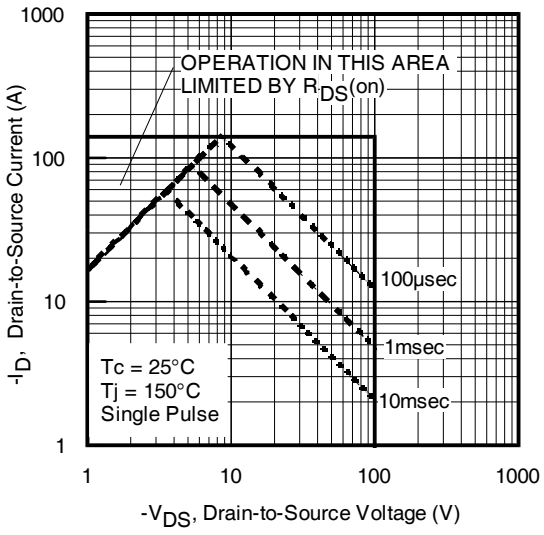


Fig 8. Maximum Safe Operating Area

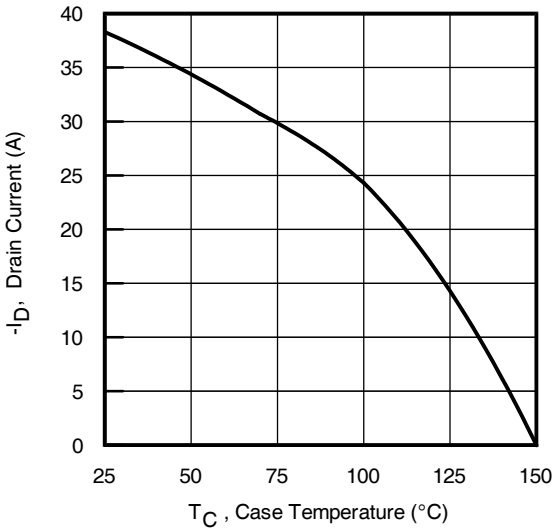


Fig 9. Maximum Drain Current vs. Case Temperature

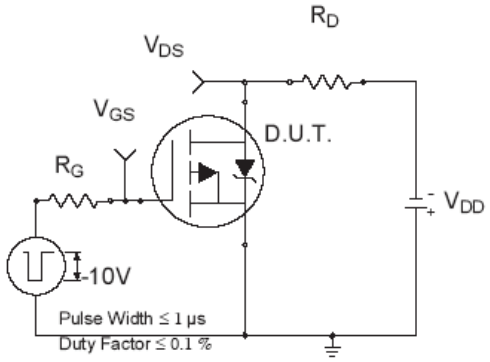


Fig 10a. Switching Time Test Circuit

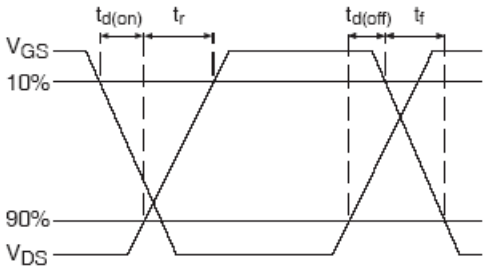


Fig 10b. Switching Time Waveforms

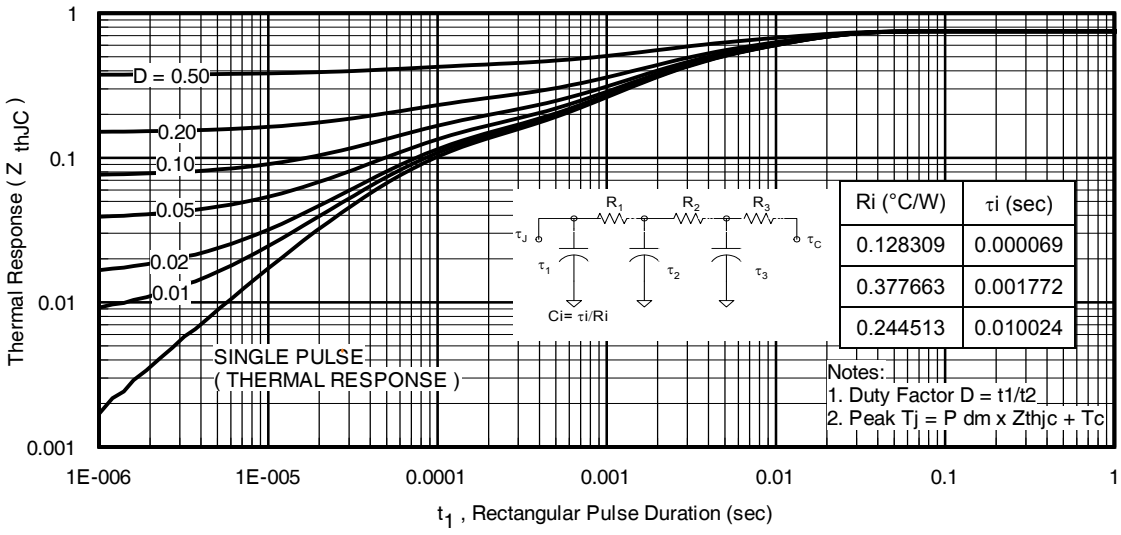


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

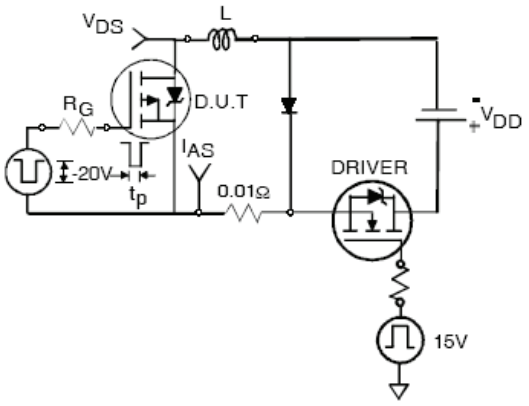


Fig 12a. Unclamped Inductive Test Circuit

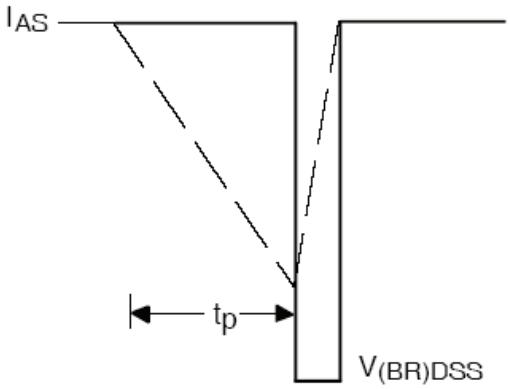


Fig 12b. Unclamped Inductive Waveforms

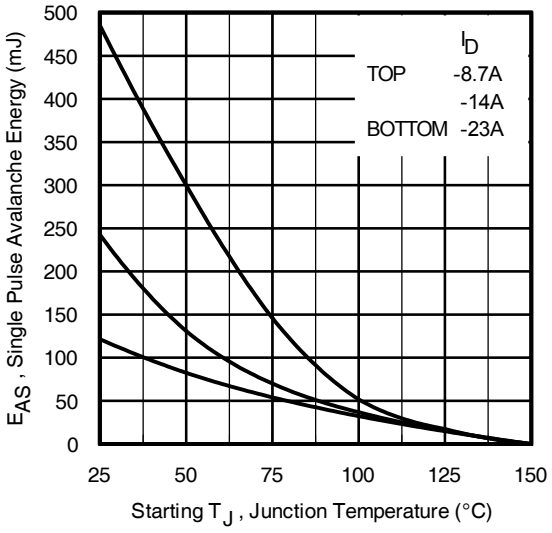


Fig 13. Maximum Avalanche Energy vs. Drain Current

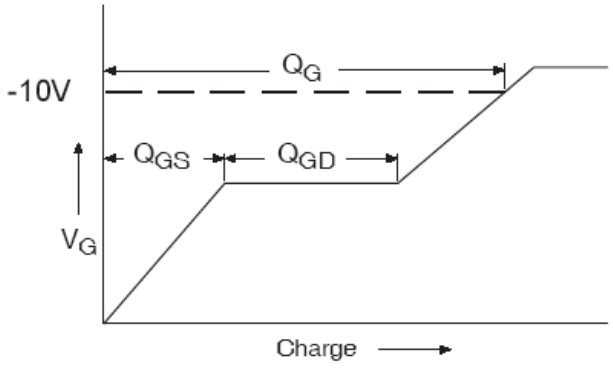


Fig 14a. Gate Charge Waveform

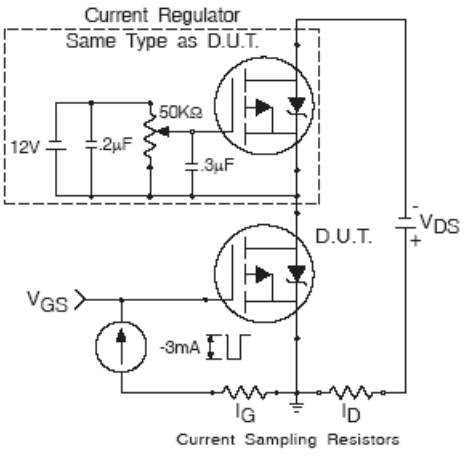
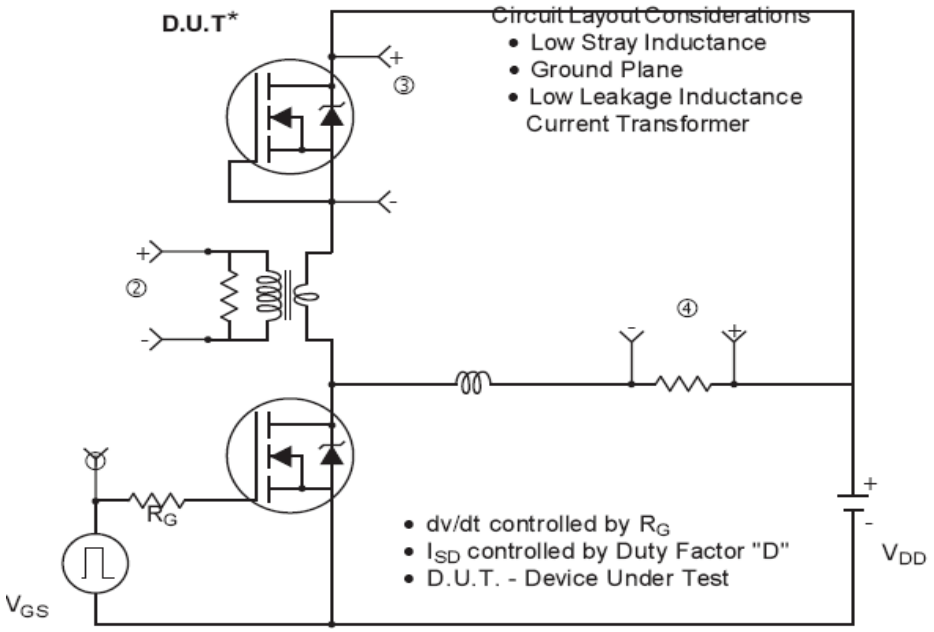
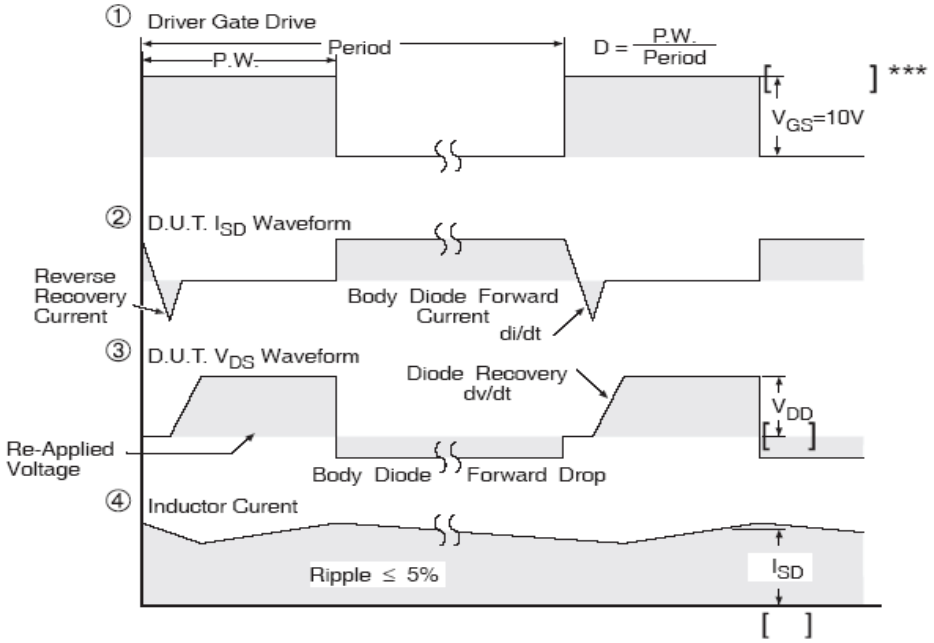


Fig 14b. Gate Charge Test Circuit



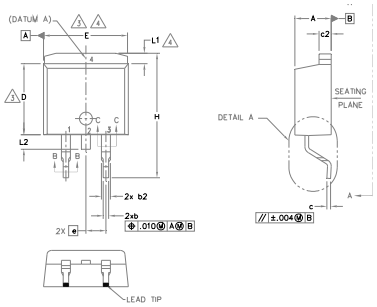
* Reverse Polarity of D.U.T for P-Channel



*** V_{GS} = 5.0V for Logic Level and 3V Drive Devices

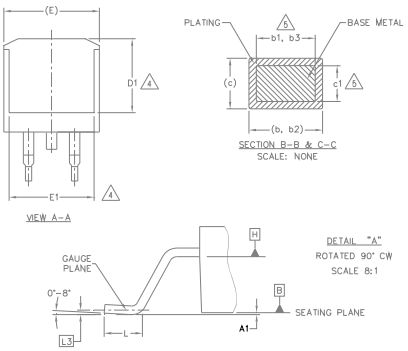
Fig 15. Peak Diode Recovery dv/dt Test Circuit for P-Channel HEXFET® Power MOSFETs

D²Pak (TO-263AB) Package Outline (Dimensions are shown in millimeters (inches))



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY AT DATUM H.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
5. DIMENSION b1, b3 AND c1 APPLY TO BASE METAL ONLY.
6. DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
7. CONTROLLING DIMENSION: INCH.
8. OUTLINE CONFORMS TO JEDEC OUTLINE TO-263AB.



SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	.160	.190	
A1	0.00	0.254	.000	.010	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	5
b2	1.14	1.78	.045	.070	
b3	1.14	1.73	.045	.068	5
c	0.38	0.74	.015	.029	
c1	0.38	0.58	.015	.023	5
c2	1.14	1.65	.045	.065	
D	8.38	9.65	.330	.380	3
D1	6.86	–	.270	–	4
E	9.65	10.67	.380	.420	3,4
E1	6.22	–	.245	–	4
e	2.54 BSC		.100 BSC		
H	14.61	15.88	.575	.625	
L	1.78	2.79	.070	.110	
L1	–	1.68	–	.066	4
L2	–	1.78	–	.070	
L3	0.25 BSC		.010 BSC		

LEAD ASSIGNMENTS

DIODES

1.– ANODE (TWO DIE) / OPEN (ONE DIE)
2, 4.– CATHODE
3.– ANODE

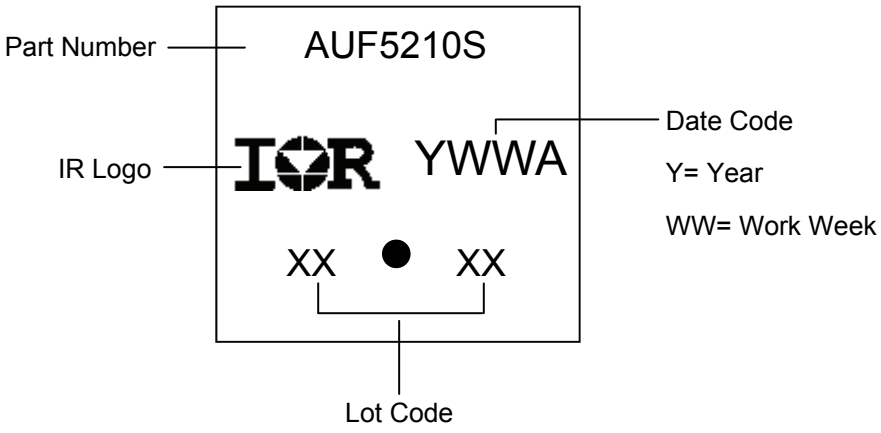
HEXFET

1.– GATE
2, 4.– DRAIN
3.– SOURCE

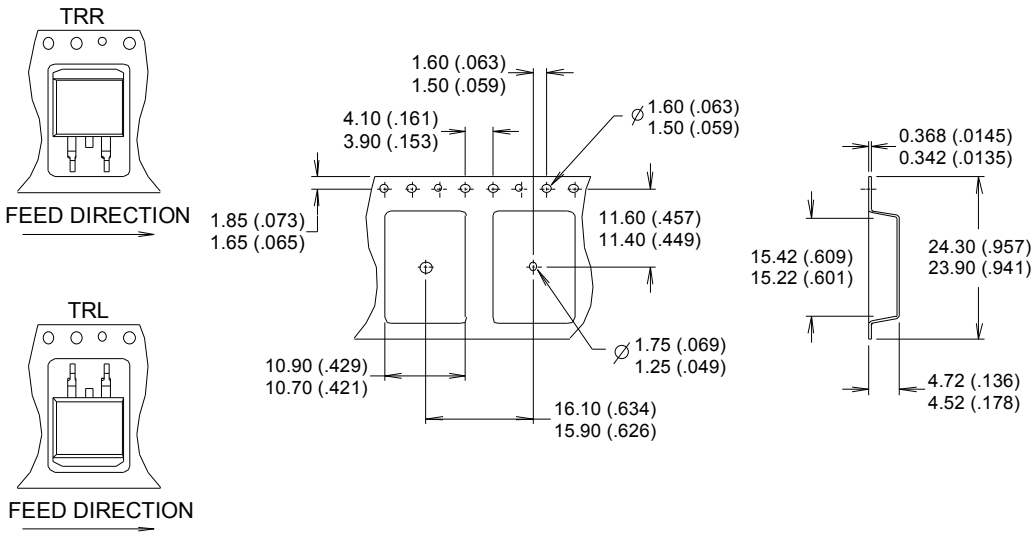
IGBTs, CoPACK

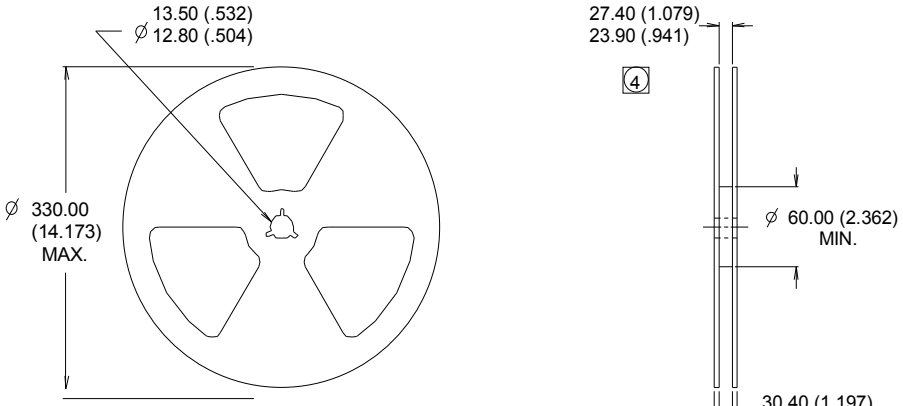
1.– GATE
2, 4.– COLLECTOR
3.– EMITTER

D²Pak (TO-263AB) Part Marking Information



D²Pak (TO-263AB) Tape & Reel Information (Dimensions are shown in millimeters (inches))





NOTES :
1. COMFORMS TO EIA-418.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION MEASURED @ HUB.
4. INCLUDES FLANGE DISTORTION @ OUTER EDGE.

Qualification Information

Qualification Level		Automotive (per AEC-Q101)	
		Comments: This part number(s) passed Automotive qualification. Infineon's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
Moisture Sensitivity Level		D^2-Pak	MSL1
ESD	Machine Model	Class M4 (+/-425V)† AEC-Q101-002	
	Human Body Model	Class H2 (/-4000V)† AEC-Q101-001	
	Charged Device Model	Class C5 (/-1125V)† AEC-Q101-005	
RoHS Compliant		Yes	

† Highest passing voltage.

Revision History

Date	Comments
9/30/2015	• Updated datasheet with corporate template • Corrected ordering table on page 1.

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